

## TechConnect Ventures

### Sprint Challenge Brief:

## High strength polymer materials for lightweighting in transportation

### BACKGROUND

In response to client needs across a range of industries, TechConnect Ventures is calling for innovations in materials and manufactures of high strength polymers for lightweighting applications, especially those that are relevant to the automotive industry. Globally, increasingly stringent environmental regulations call for steadily increasing gas mileage and emissions requirements. Meeting these new efficiency requirements can be achieved in various ways, chief among them is to reduce the overall vehicle weight by employing lighter weight materials than traditional steel parts. Polymers offer significant functional and performance advantages such as easy processing, high strength, corrosion resistance, and lightweight. This call focuses on the great need to utilize these polymers in the automotive sector beyond non load bearing decorative components to the more demanding high strength structural and functional components.

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### REQUIREMENTS

Solvers submitting an Entry should make efforts to address the following key focus areas in their Submission (if applicable):

- Carbon fiber-based composites
- Non-carbon-based composites
- Bio based composite resins
- Materials for high strength functional and structural components
- Materials with excellent impact and heat resistance properties
- Potential for manufacturing with high dimensional accuracy

## BUSINESS OPPORTUNITY FOR SOLVERS

All complete and eligible Entries will be included in our exclusive Innovation Opportunity Report that will be presented to the innovation-seeking clients and partners. Solvers with well-matched capabilities may be contacted directly by consortium members to discuss potential partnership opportunities. Top-rated Entries may also be invited to register or participate in an upcoming TechConnect Ventures event or pitch program.

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## PARTICIPATION RULES & GUIDELINES

1. You must complete the provided Submission webform on the Sprint Submission page.
2. You are encouraged to submit a short presentation or pitch deck. A template is available on the Submission page.
3. **DO NOT INCLUDE ANY INFORMATION MARKED CONFIDENTIAL, PROPRIETARY, SENSITIVE OR CLASSIFIED. SUBMISSIONS MARKED AS SUCH WILL NOT BE SHARED WITH CLIENTS.**

Solvers should review the [Rules](#) and [Guidelines](#) provided on the Sprint page for details about participation, including submission criteria, eligibility information, and more.

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**QUESTIONS?** Contact Executive Director, Nick Kacsandi at [info@techconnectventures.com](mailto:info@techconnectventures.com)